L Number	Hits	Search Text	DB	Time stamp
1	34	"5108941"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:07
3	37385	trench and substrate and (interconnection near layer or metal layer$1 or metallization$1 or polysilion near layer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:09
4	6	trench and substrate and (interconnection near layer or metal layer$1 or metallization$1 or polysilion near layer$1) and "5108941"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:32
5	4307	trench and substrate and (interconnection near layer or metal layer$1 or metallization$1 or polysilion near layer$1) and (guard near ring or encircle or surround$3) same trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:35
6	1	(trench and substrate and (interconnection near layer or metal layer$1 or metallization$1 or polysilion near layer$1) and (guard near ring or encircle or surround$3) same trench) and pon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:35
7	1	(trench and substrate and (interconnection near layer or metal layer$1 or metallization$1 or polysilion near layer$1) and (guard near ring or encircle or surround$3) same trench) and pon.inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:35
8	180	pon.inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:37
9	2	pon.inv. and trench and substrate and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:37
10	2	pon.inv. and trench and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 07:37
11	3	pon.inv. and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 08:28
12	2	"5686330"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 08:28
13	2	"5686330" and guard near ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 08:28
14	2	("5686330" and guard near ring) and trench and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 08:37

15	6	"5260227"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/06 08:37